

- NOTES:
1. MATERIALS:
 TERMINALS: COPPER ALLOY
 HOUSING: HIGH TEMP THERMOPLASTIC, COLOR: BLACK, 94V-0
 FLEX CIRCUIT - POLYIMIDE
 HARDBOARD - FR4
 2. PLATING: SELECTIVE GOLD IN CONTACT AREA OVER NICKEL, TIN ON TAIL OVER NICKEL.
 3. PACKAGING: PARTS TO BE PACKAGED PER PK-110299-001.
 4. FOR POINT-TO-POINT PINOUT ON ALL CIRCUIT SIZES SEE SHEET 2.
 5. CONFORMS TO IPC-6011 "GENERIC PERFORMANCE SPECIFICATION FOR PRINTED BOARDS".
 IPC-6013A "QUALIFICATION AND PERFORMANCE SPECIFICATION FOR FLEXIBLE PRINTED BOARDS".
 IPC-A-610, CLASS 2 "ACCEPTABILITY OF ELECTRONIC ASSEMBLIES".
 IPC-A-600, CLASS 2 ACCEPTABILITY OF PRINTED BOARDS".
 6. ELECTRICAL TESTING: 100% CONTINUITY CHECK.
 7. ASSEMBLY IS RoHS COMPLIANT.

INITIAL RELEASE EC NO: CFP2008-0004 DRWNSCHMIDG 2008/03/11 CHKD: APPR: 2008/05/02	DESCRIPTION
REV A	

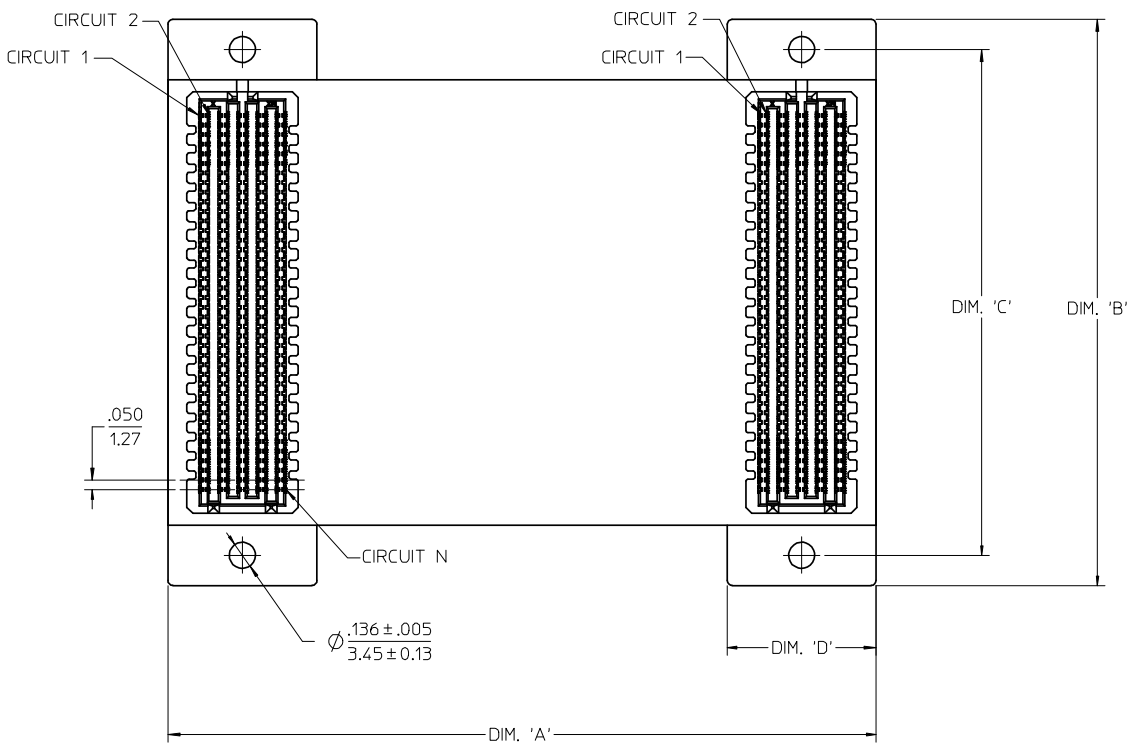
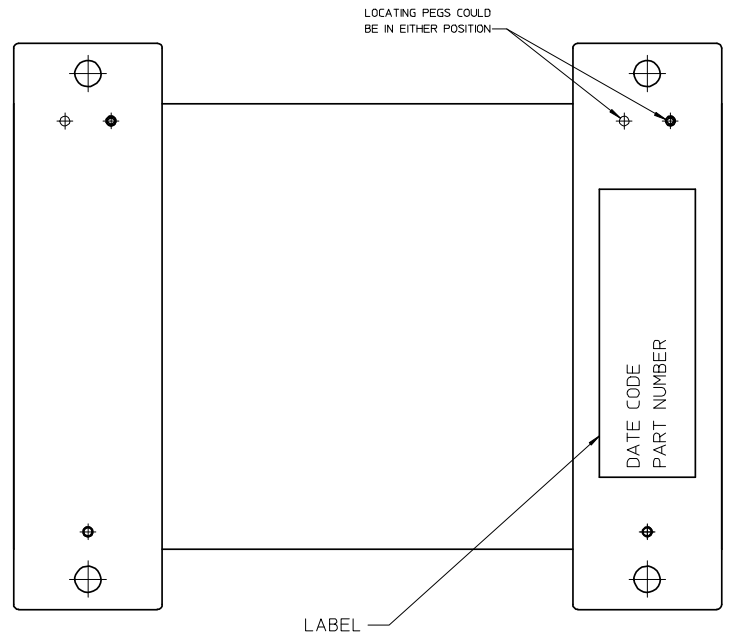
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)
$\nabla=0$	mm INCH
$\nabla=0$	4 PLACES ± --- ± ---
	3 PLACES ± --- ± .010
	2 PLACES ± 0.25 ± ---
	1 PLACE ± --- ± ---
	ANGULAR ± 1/2°
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM/IN		2:1	METRIC	
DRAWN BY	DATE	TITLE		
DSCHMIDGALL	10/25/2006	SEARAY (PLUG) FLEX CIRCUIT ASSEMBLY		
CHECKED BY	DATE	MOLEX INCORPORATED		
DSCHMIDGALL	10/25/2006	SD-110299-001		
APPROVED BY	DATE	SHEET NO. 1 OF 4		
MATERIAL NO.		DOCUMENT NO.		
SEE CHART				
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

13	12	11	10	9	8	7	6	5	4	3	2	1	
CIRCUIT SIZE	FLEX ASSEMBLY MATERIAL NUMBER	HOUSING HEIGHT	DIM. A	DIM. B	DIM. C	DIM. D	NUMBER OF POSITIONS PER ROW		NUMBER OF ROWS				
300	110299-0002	.260/6.60	3.690/93.73	2.765/70.23	2.450/62.23	.775/19.69	30		10				
	110299-0003	.280/7.11	3.690/93.73										

SEE SHEET 2 FOR PIN OUT

SEE SHEET 1 EC NO: CFP2008-0004 DRWNSCHMIDG 2008/03/11 CHKD: APPR: 2008/05/02	QUALITY SYMBOLS =0 =0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± .---</td> <td>± .---</td> </tr> <tr> <td>3 PLACES</td> <td>± .---</td> <td>± .010</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.25</td> <td>± .---</td> </tr> <tr> <td>1 PLACE</td> <td>± .---</td> <td>± .---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± .---	± .---	3 PLACES	± .---	± .010	2 PLACES	± 0.25	± .---	1 PLACE	± .---	± .---	DIMENSION STYLE MM/IN DRAWN BY: DSCHMIDGALL DATE: 10/25/2006 CHECKED BY: DATE: APPROVED BY: DATE:	SCALE: 1:1 DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: SEARAY (PLUG) FLEX CIRCUIT ASSEMBLY
		mm	INCH																	
	4 PLACES	± .---	± .---																	
	3 PLACES	± .---	± .010																	
2 PLACES	± 0.25	± .---																		
1 PLACE	± .---	± .---																		
MATERIAL NO. SEE CHART DOCUMENT NO. SD-110299-001 SHEET NO. 3 OF 4	MOLEX INCORPORATED																			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																		
A	REV	SIZE C																		



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DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY DSCHMIDGALL	DATE 10/25/2006	TITLE SEARAY (PLUG) FLEX CIRCUIT ASSEMBLY		
CHECKED BY	DATE	MOLEX INCORPORATED		
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		4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	mm INCH ± --- ± --- ± .010 ± --- ± --- ± --- ± ---	DRAWN BY DSCHMIDGALL	DATE 10/25/2006	TITLE SEARAY (PLUG) FLEX CIRCUIT ASSEMBLY			
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